

PRESS RELEASE

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Microstructured Wafertable for use in the Semiconductor market

BERLINER GLAS offers microstructured wafer tables for the use in the Semiconductor Industrie for a controlled positioning and holding of silicon wafers for exposure and processing.

With a microstructured surface, the spaces between the burrs eliminate adhesion and make it easier to clean the wafer tables. The structure is responsible for a stable and controlled positioning of the wafers, which have a maximum thickness of 1 mm and are extremely susceptible to breakage.

The wafers are held in place on the wafer table by hypobaric pressure. On an unstructured, planar surface, this pressure would cause unwanted adhesion, complicate removal and risk breaking the wafer. Excellent plane parallelism is achieved over the bearing surface of the burrs.

Values of up to 80 nm are possible for 300-mm tables, depending on the material. The structured surfaces can be matt or transparent. Functional layers can be applied after structuring, e.g., for antistatic effects or with antiabrasive properties.

Berliner Glas manufactures structured glass and glass ceramics as large as approximately 400 x 400 mm and about 12 mm thick.

Contact:

Berliner Glas KGaA
Herbert Kubatz GmbH & Co.
Waldkraiburger Str. 5
D-12347 Berlin
www.berlinerglas.com

Astrid Freiding
Marketing/Communications
Phone: +49 30 60905-368
Fax: +49 30 60 90 5-100
freiding@berlinerglas.de